

ADOPTION NOTICE

IPC-2251, "Design Guide for the Packaging of High Speed Electronic Circuits", was adopted on 14 August 2009 for use by the Department of Defense (DoD). Proposed changes by DoD activities must be submitted to the DoD Adopting Activity: Defense Logistics Agency, Defense Supply Center, Columbus, ATTN: DSCC-VAC, P.O. Box 3990, Columbus OH 43218-3990 or 5998.Documents@dla.mil. Copies of this standard may be purchased or downloaded from the IPC - Association Connecting Electronics Industries (IPC), 3000 Lakeside Drive, Suite 309 S, Bannockburn, IL 60015-1249 or at URL: <http://www.ipc.org>.

Custodians:
Army - CR
Navy - EC
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Adopting Activity:
DLA - CC

Project: 5998-2009-060

Review Activities:
Air Force - 99

NOTE: The activities listed above were interested in this document as of the date of this document. Since organizations and responsibilities can change, you should verify the currency of the information above using the ASSIST Online database at <http://assist.daps.dla.mil/>.